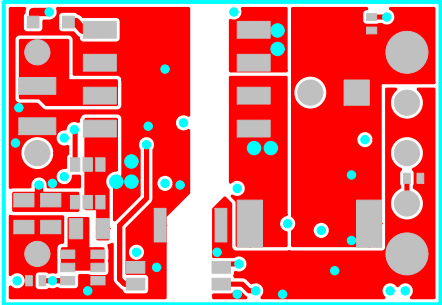
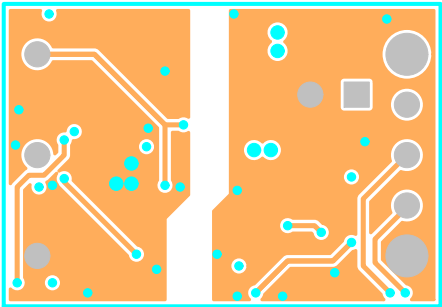
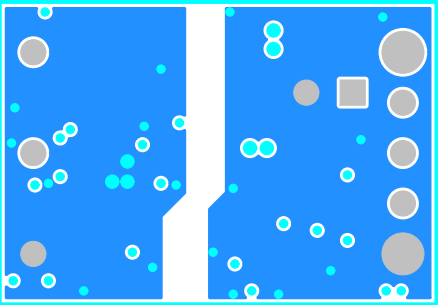




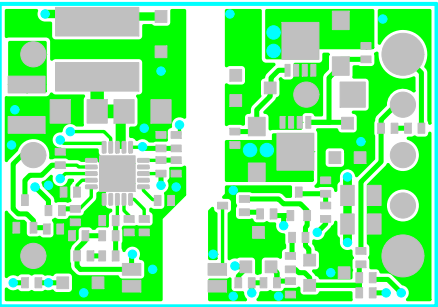
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6886		Rev. A	L1											
Date: {Start Date}	Filename: PMP6886 A	Engineer: Brian K.	PCB Dsgnr: Brian K.		Modified Date: {Modification Date}						Software PADS			



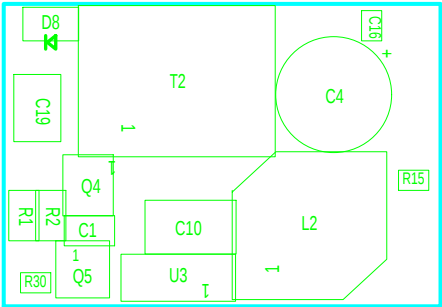
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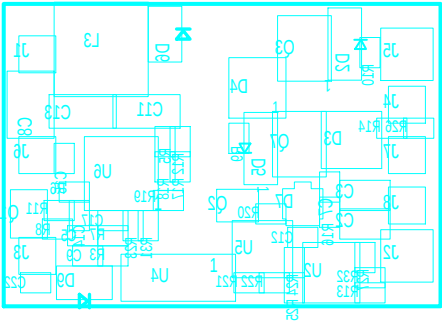
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Board No. PMP6886		Rev. A			L3									
Date: {Start Date}	Filename: PMP6886 A	Engineer: Brian K.	PCB Dsgnr: Brian K.			Modified Date: {Modification Date}					Software PADs			



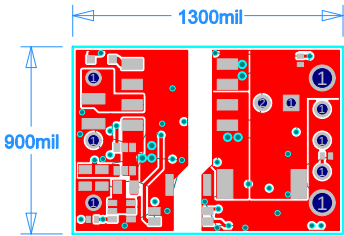
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Board No. PMP6886		Rev. A				L4								
Date: {Start Date}	Filename: PMP6886 A	Engineer: Brian K.	PCB Dsgnr: Brian K.		Modified Date: {Modification Date}						Software PADs			



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6886		Rev. A	L1									TA		
Date: {Start Date}	Filename: PMP6886 A	Engineer: Brian K.	PCB Dsgnr: Brian K.		Modified Date: {Modification Date}							Software	PADs	



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6886		Rev. A			L4							BA		
Date: {Start Date}	Filename: PMP6886 A	Engineer: Brian K.	PCB Dsgnr: Brian K.		Modified Date: {Modification Date}						Software	PADs		



TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6886	Rev. A	L1											FB
Date: (Start Date)	Filename: PMP6886 A	Engineer: Brian K.		PCB Dsgnr: Brian K.		Modified Date: (Modification Date)					Software PADs		

FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☐ LAYER 2 ☐ NONE	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT	
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006		☐ SINGLE SIDED ☒ 4 LAYER ☐ 8 LAYER ☐ OTHER _____	☐ 2 LAYER ☐ 6 LAYER ☐ 10 LAYER

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE:

PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c.

GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK:

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES:

UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING:

HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH:

PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS

AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND:

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS:

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP:

BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION:

PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES:

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER:

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES:

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

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